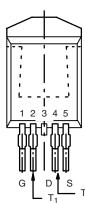


**Vishay Siliconix** 

ROHS COMPLIANT

# P-Channel 55-V (D-S) MOSFET with Sensing Diode

PRODUCT SUMMARY				
V <sub>(BR)DSS</sub> (V)	r <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A)		
- 55	0.011 at V <sub>GS</sub> = - 10 V	- 60 <sup>a</sup>		
	0.0175 at V <sub>GS</sub> = - 4.5 V	- 60 <sup>a</sup>		



### D<sup>2</sup>PAK-5L

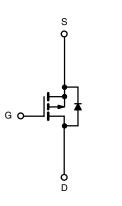


### **FEATURES**

- TrenchFET<sup>®</sup> Power MOSFETS Plus Temperature Sensing Diode
- 175 °C Junction Temperature
- Low Thermal Resistance Package

#### **APPLICATIONS**

Industrial





P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	T <sub>C</sub> = 25 °C, unless oth	erwise noted			
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	- 55	v	
Gate-Source Voltage	V <sub>GS</sub>	± 20	V		
Continuous Drain Current $(T_J = 175 \ ^{\circ}C)^d$	T <sub>C</sub> = 25 °C	1-	- 60 <sup>a</sup>		
	T <sub>C</sub> = 100 °C	I <sub>D</sub>	- 60 <sup>a</sup>		
Pulsed Drain Current	I <sub>DM</sub>	- 250	А		
Continuous Diode Current (Diode Conduction) <sup>d</sup>	۱ <sub>S</sub>	- 60 <sup>a</sup>			
Avalanche Current	I <sub>AR</sub>	- 60 <sup>a</sup>			
Repetitive Avalanche Energy <sup>b</sup>	L = 0.1 mH	E <sub>AR</sub>	180	mJ	
	T <sub>C</sub> = 25 °C	Р	200 <sup>c</sup>	w	
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 25 °C	– P <sub>D</sub>	3.75 <sup>d</sup>	VV I	
Operating Junction and Storage Temperature Ra	inge	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Limit	Unit		
Junction-to-Ambient <sup>d</sup>	PCB Mount <sup>d</sup>	R <sub>thJA</sub>	40	°C/W		
Junction-to-Case		R <sub>thJC</sub>	0.75	0/11		

Notes:

a. Package limited.

b. Duty cycle  $\leq$  1 %.

c. See SOA curve for voltage derating.

d. When mounted on 1" square PCB (FR-4 material).

\* Pb containing terminations are not RoHS compliant, exemptions may apply.

# SUM60P05-11LT

## Vishay Siliconix



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static		· · · ·					
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0 V, I_D = -250 \mu A$	- 55			v	
Gate-Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{DS} = -250 \ \mu A$	- 1				
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
	I <sub>DSS</sub>	V <sub>DS</sub> = - 44 V, V <sub>GS</sub> = 0 V			- 1		
Zero Gate Voltage Drain Current		$V_{DS}$ = - 44 V, $V_{GS}$ = 0 V, $T_{J}$ = 175 °C			- 250	μΑ	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = - 5 V, V <sub>GS</sub> = - 10 V	- 120			Α	
		V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 30 A		0.009	0.011	Ω	
		$V_{GS}$ = - 10 V, I <sub>D</sub> = - 30 A, T <sub>J</sub> = 125 °C			0.0175		
Drain-Source On-State Resistance <sup>a</sup>	<sup>r</sup> DS(on)	$V_{GS}$ = - 10 V, I <sub>D</sub> = - 30 A, T <sub>J</sub> = 175 °C			0.022		
		V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 20 A			0.0175		
Sense Diode Forward Voltage	V <sub>FD</sub>	V <sub>DS</sub> = - 25 V, I <sub>F</sub> = - 250 μA	- 770		- 830		
Sense Diode Forward Voltage Increase	$\Delta V_{F}$	From $I_F = -125 \ \mu A$ to $I_F = -250 \ \mu A$	- 25		- 55	mV	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 25 V, I <sub>D</sub> = - 30 A		50		S	
Dynamic <sup>b</sup>		•		•	• •		
Input Capacitance	C <sub>iss</sub>			6450		pF	
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 V$ , $V_{DS} = -25 V$ , f = 1 MHz		1050			
Reverse Transfer Capacitance	C <sub>rss</sub>			520			
Total Gate Charge <sup>c</sup>	Qg			107		nC	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS} = -30$ V, $V_{GS} = -10$ V, $I_{D} = -60$ A		28			
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			22			
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			15	25		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD}$ = - 30 V, $R_L$ = 0.6 $\Omega$		190	325	ns	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_{D}\cong$ - 60 A, $V_{GEN}$ = - 10 V, $R_{G}$ = 2.5 $\Omega$		145	220		
Fall Time <sup>c</sup>	t <sub>f</sub>			265	450		
Source-Drain Diode Ratings and Char	acteristics	Γ <sub>C</sub> = 25 °C <sup>b</sup>					
Continuous Current	۱ <sub>S</sub>				- 60	٨	
Pulsed Current	I <sub>SM</sub>	M			- 200	A	
Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>F</sub> = - 60 A, V <sub>GS</sub> = 0 V		- 1.1	- 1.5	V	
Reverse Recovery Time	t <sub>rr</sub>			55	110	ns	
Peak Reverse Recovery Current	I <sub>RM(REC)</sub>	I <sub>F</sub> = - 60 A, di/dt = 100 A/μs		- 1.6	- 2.0	Α	
Reverse Recovery Charge	Q <sub>rr</sub>	1 1		0.04	12	μC	

Notes:

a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %.

b. Guaranteed by design, not subject to production testing.

c. Independent of operating temperature.

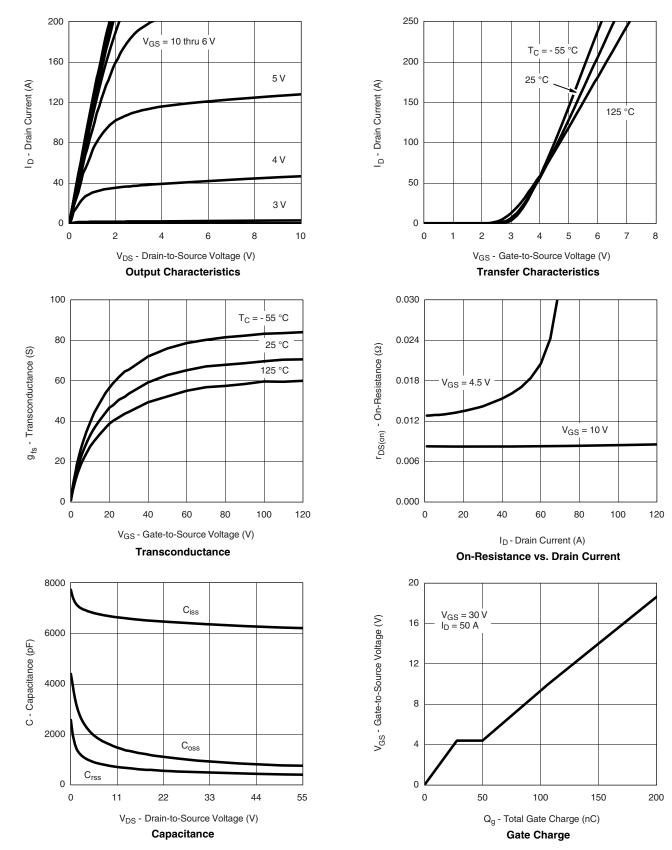
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



# SUM60P05-11LT

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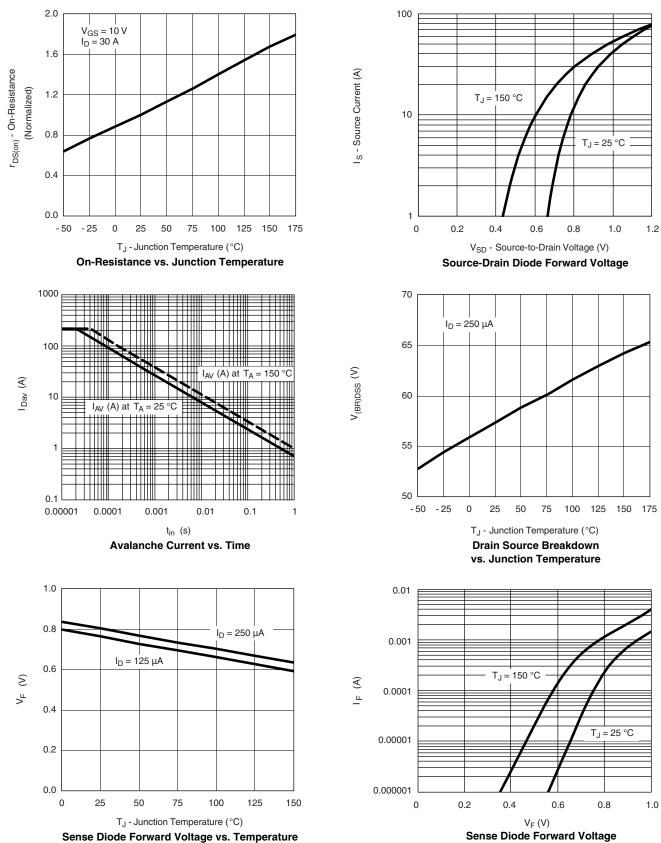




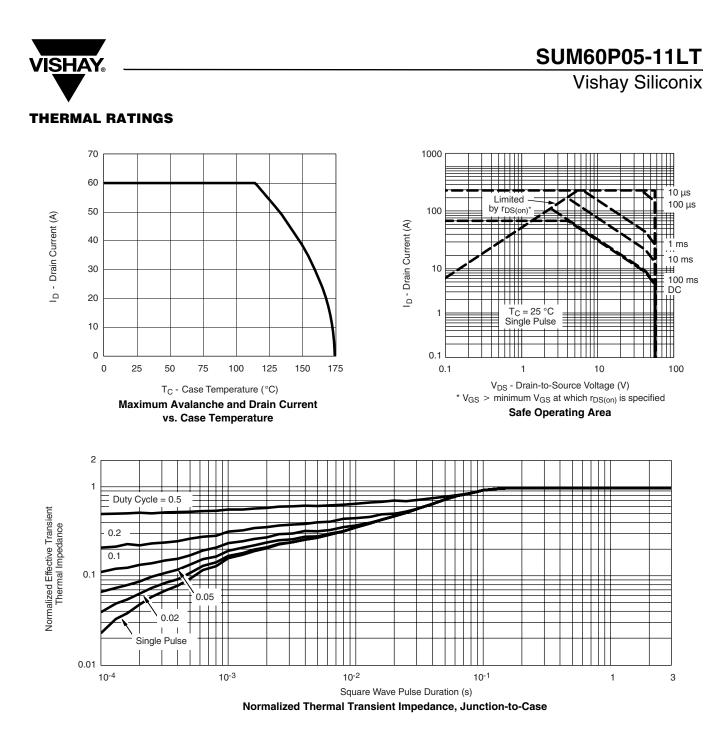
Document Number: 71748 S-80274-Rev. B, 11-Feb-08

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### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



**/ISHA** 

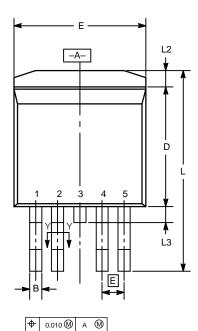


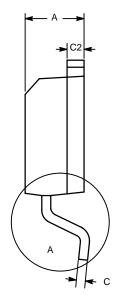
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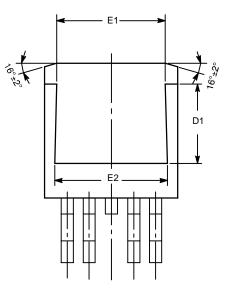


TO-263 (D<sup>2</sup>PAK): 5 LEADS

(For Lead Thickness 25 mil)





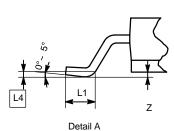


INCHES

Max

0.002

Min



M Section Y-Y

#### NOTES:

- 1. Plane B includes maximum features of heat sink tab and plastic.
- 2. No more than 25% of L1 can fall above seating plane by maximum 8 mils.
- 3. Pin-to-pin coplanarity maximum 4 mils.
- 4. Z not to exceed 10 mils.

Α	0.170	0.185		
В	0.028	0.039		
B1	0.028	0.035		
С	0.018	0.028		
C1	0.018	0.025		
C2	0.045	0.055		
D	0.340	0.380		
D1	0.220	0.255		
Е	0.385	0.405		
E1	0.310	0.340		
E2	0.355	0.375		
Ш	0.067	0.067 BSC		
L	0.575	0.625		
L1	0.090	0.110		
L2	0.040	0.055		
L3	0.050	0.070		
L4	0.010 BSC			

Μ

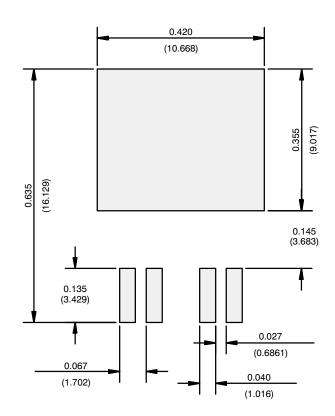
ECN: T-01063—Rev. B, 07-May-01 DWG: 5864

Dim



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### **RECOMMENDED MINIMUM PADS FOR D<sup>2</sup>PAK: 5-Lead**



Recommended Minimum Pads Dimensions in Inches/(mm)

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